

IN THE SPECIFICATION

Please amend paragraph 0102 of the present specification as follows:

[0102] In still further variants, the external elements used with the framed sheet may include one or more individual semiconductor chips, which can be attached to the framed sheet simultaneously or ~~individually~~ individually as taught in the aforementioned United States Patent 5,798,286. In yet another variant, the frame may be used as a fixture for encapsulation of the assembly. Processes for encapsulation of an assembly using a frame to constrain the encapsulant are taught in certain embodiments of United States Patent No. 5,776,796 and in copending, commonly assigned United States Patent Application 09/067,698 filed April 28, 1998, the disclosures of which are hereby incorporated by reference herein. In still further variants, the sheet can be removed from the frame after processing and assembled to chips or other elements in the same manner as a conventional sheet.